

## Characterizing the interfacial composition of organic bulk heterojunction solar cells

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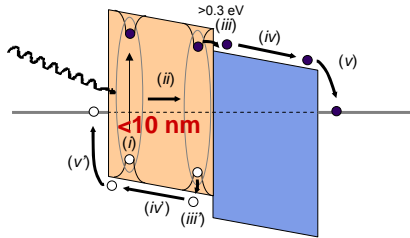
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# Organic Photovoltaics (OPV)

## Planar Heterojunction (PHJ)



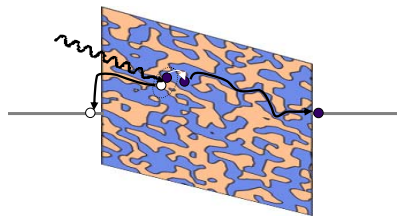
Cathode (e.g., ITO) "Donor" (e.g., P3HT) "Acceptor" (e.g., PCBM) Anode (e.g. Ag)



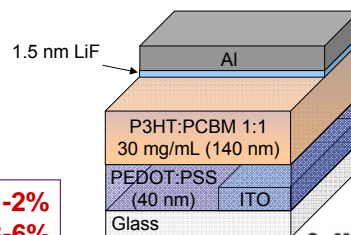
- Power conversion efficiencies are still relatively low, and vary widely depending on processing.
- Factors contributing to these limitations are not well understood.

**$PCE_{PHJ} \sim 1-2\%$**   
 **$PCE_{BHJ} \sim 3-6\%$**

## Bulk Heterojunction (BHJ)



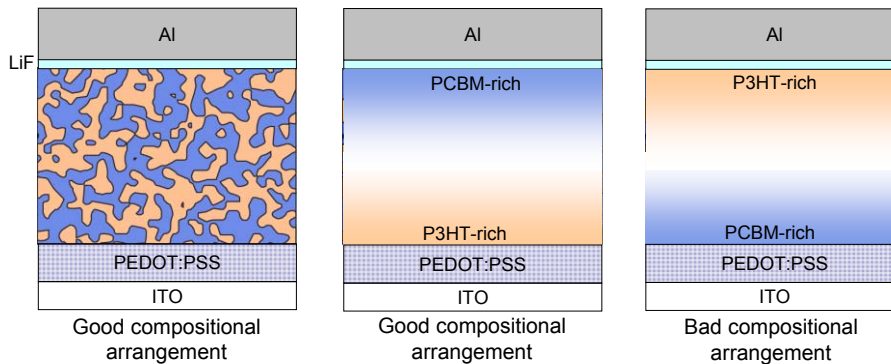
Cathode (e.g., ITO) Donor/Acceptor Blend (e.g., 1:1 P3HT:PCBM) Anode (e.g. Ag)



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# The Importance of Film Composition

- Film composition may have critical effects on OPV performance.
- Bulk composition is important for percolation pathways and may affect carrier mobility.
  - TEM: Moon *et al.*, *Nano Lett.* **9**, 230 (2009); Anderson *et al.*, *Nano Lett.* **9**, 853 (2009);
- Interface composition plays an important role in carrier extraction from an OPV.
  - XPS: Xu *et al.*, *Adv. Funct. Mater.* **19**, 1227 (2009)
  - NEXAFS/TFT: Germack and Chan *et al.*, *Appl. Phys. Lett.* **94**, 233303 (2009)

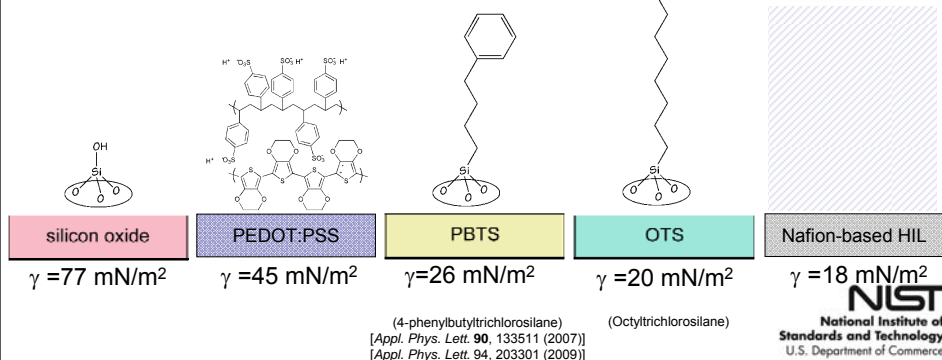
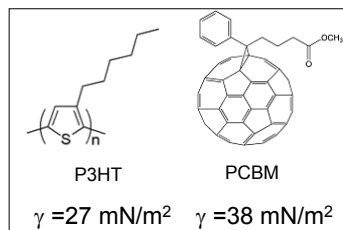


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## Control over the Interface Composition

- Interface composition driven by interface chemistry or surface/interface energy minimization.

- Film/air interface
  - Film/substrate interface
- ➔
- Tailor by using different substrates.
  - Self-assembled monolayers make model surfaces.



## Sample Preparation

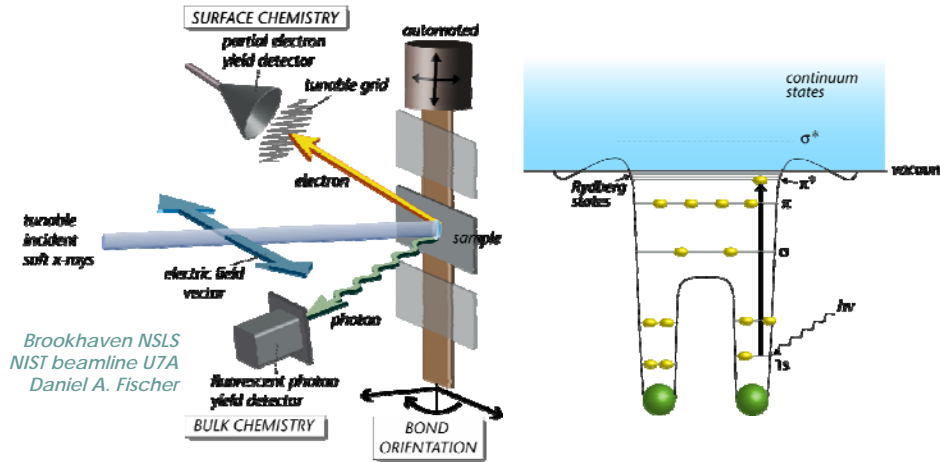
- **Self-assembled monolayers**
  - **OTS8:**  
2 mM OTS8 in hexadecane overnight.  
Sonication in chloroform, isopropanol, and DI-water; 10 min at 150 °C.
  - **PBTS:**  
10 mM PBTS in toluene overnight.†  
Sonication in toluene, acetone, and isopropanol; 10 min at 150 °C.
- **Hole-injection layers**
  - **PEDOT:PSS:**  
Spin coat at 5000 rpm for 1 min; 60 min at 150 °C.
  - **Nafion-based HIL:**  
Spin coat at 2500 rpm for 1 min; 60 min at 150 °C.
- **Bulk heterojunction film**
  - 30 mg/mL 1:1 P3HT:PCBM by weight in o-dichlorobenzene at 60 °C.
  - Spin coat at 500 rpm for 1 min.
  - “As cast” (AC) = solvent annealed.‡
  - “Annealed” (AN) = 140 °C for 40 min.

† Kumaki, D. et al. *Appl. Phys. Lett.* **90**, 133511 (2007)

‡ Li, G. et al. *Adv. Funct. Mater.* **17**, 1636-1644 (2007)

## Characterizing the Interfacial Composition

- Near Edge X-ray Absorption Fine Structure (NEXAFS)



### Strengths for Organic Electronics:

- Detects C, N, O, & F bonds.
- High sensitivity to  $\pi$  bonding.
- Measures orientation.
- Surface sensitive (<5 nm).

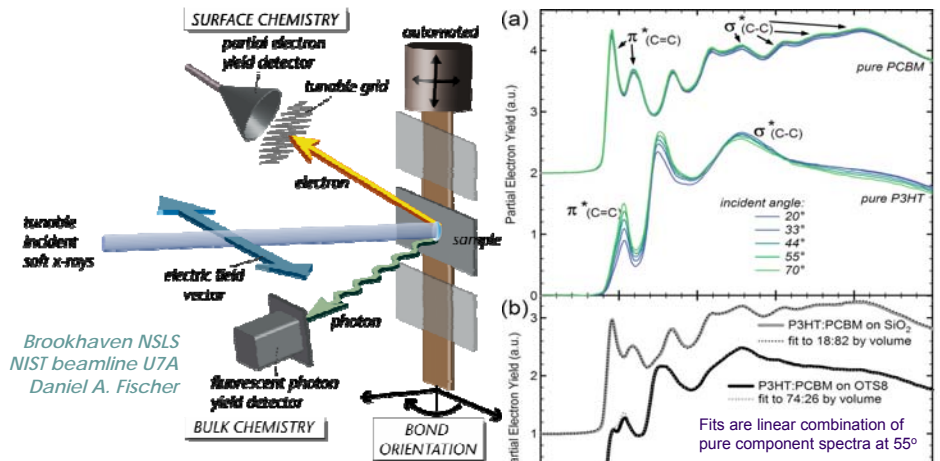
### Does not Measure:

- Crystal packing style, prevalence, size, shape.
- HOMO, LUMO, or bandgaps.
- Vibrational or rotational structure.

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## Characterizing the Interfacial Composition

- Near Edge X-ray Absorption Fine Structure (NEXAFS) [Germack & DeLongchamp]



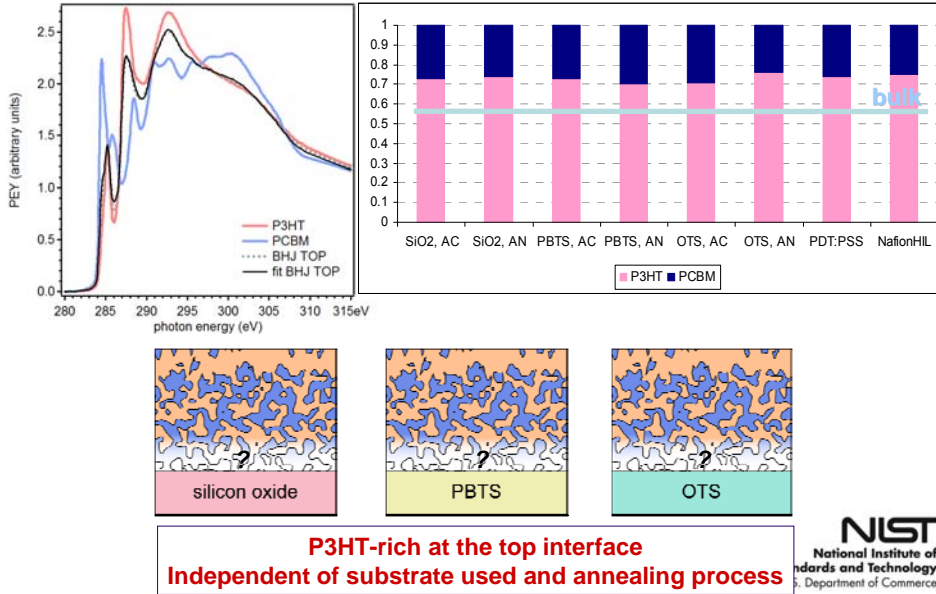
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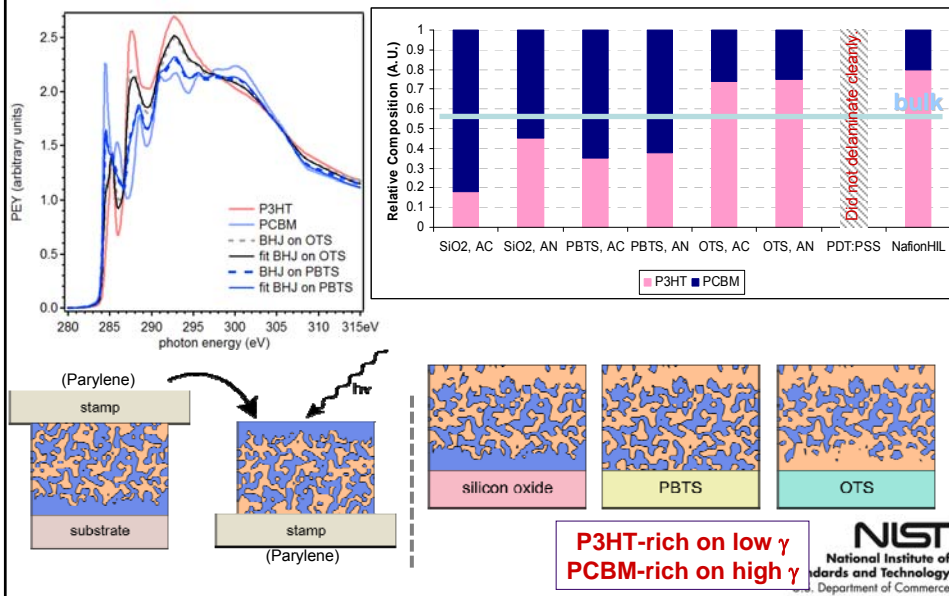
## BHJ Film Composition at the Air Interface

- **Corresponds to the top contact interface.**



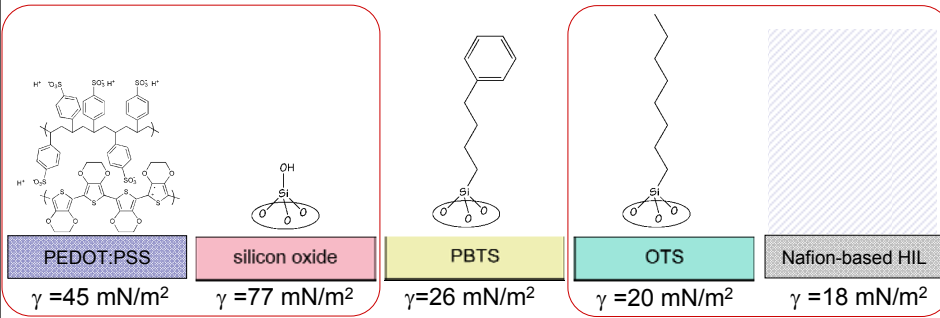
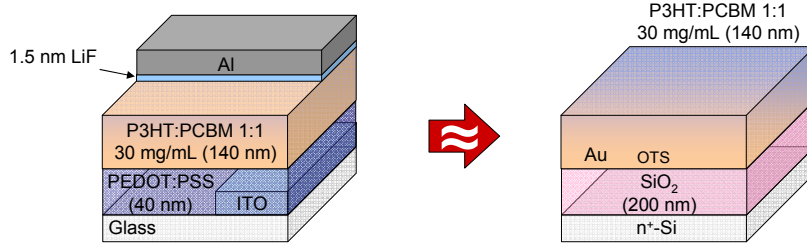
## BHJ Film Composition at the Bottom Interface

- **Surface energy controlled by SAMs**



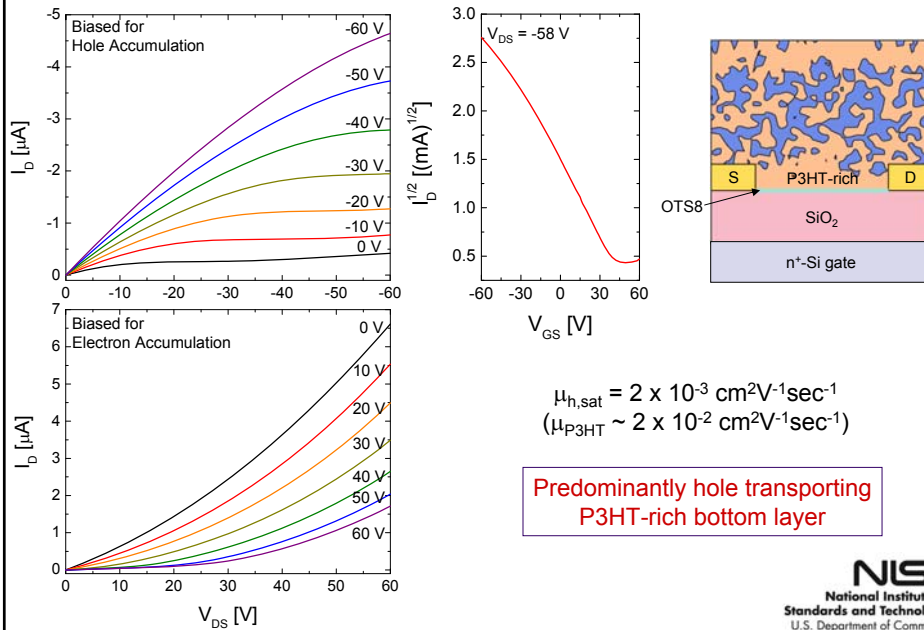
## Characterizing the Interfacial Composition

- Electrical Characterization of BHJ Thin Film Transistors

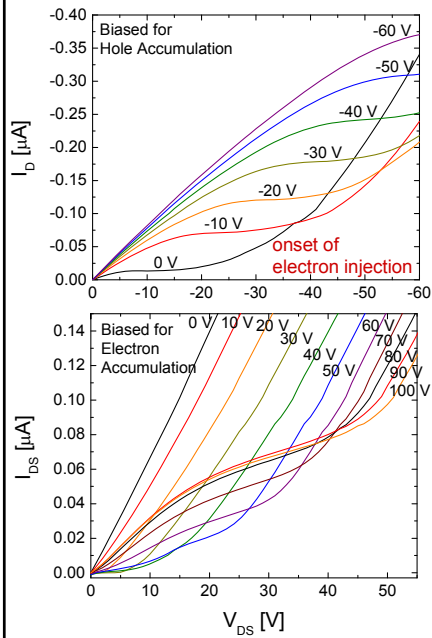


Morana et al., *Adv. Funct. Mater.* **17**, 3274 (2007); Germack and Chan et al., *Appl. Phys. Lett.* **94**, 233303 (2009)

## BHJ TFTs on Octyltrichlorosilane (OTS8)



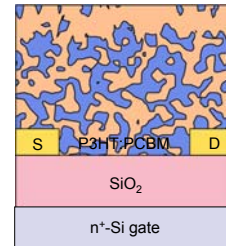
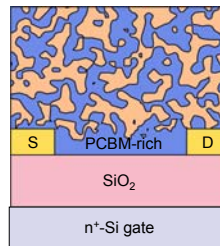
## BHJ TFTs on SiO<sub>2</sub>



### Hole & Electron Transport Two possibilities:

Ambipolar transport  
PCBM-rich layer

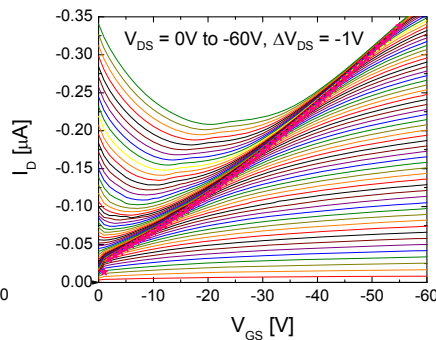
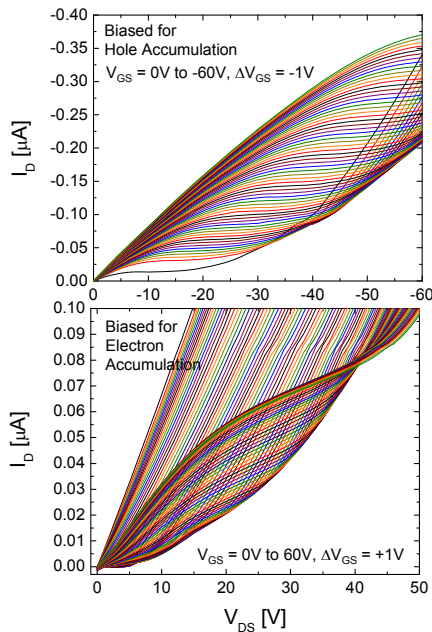
Tandem transport  
P3HT:PCBM layer



Can we tell the difference?

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## BHJ TFT on SiO<sub>2</sub>: Carrier mobility



Hole mobility observed

$$\mu_{h,sat,ox} = 1 \times 10^{-4} \text{ cm}^2\text{V}^{-1}\text{sec}^{-1}$$

(Could not get hole transport in PCBM on SiO<sub>2</sub>)

Tandem transport through P3HT and PCBM

$$\mu_{h,sat,ox} \ll \mu_{h,sat,OTS8}$$

Less P3HT at the SiO<sub>2</sub> interface, PCBM-rich

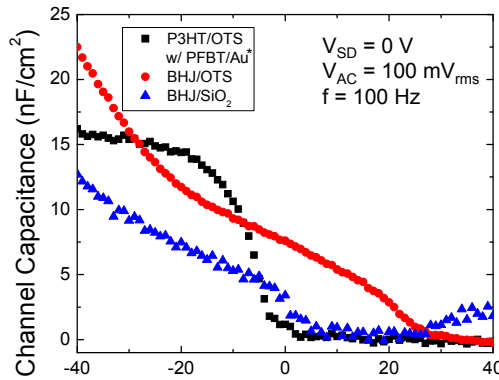
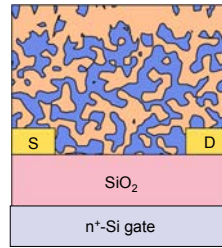
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## Capacitance Voltage on BHJ TFTs

- Induce charges in the channel at the dielectric/organic interface.

$$C = C_S + C_D + C_C \rightarrow \frac{\epsilon_{Si}\epsilon_0 A_{P3HT}}{d} \quad \text{Hole accumulation}$$

$$\frac{\epsilon_{Si}\epsilon_0 A_{PCBM}}{d} \quad \text{Electron accumulation}$$



More hole accumulation on OTS  
Larger P3HT areas on OTS

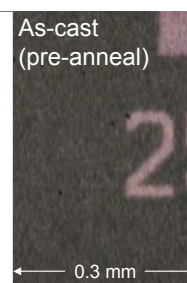
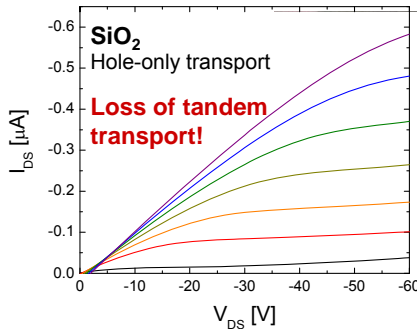
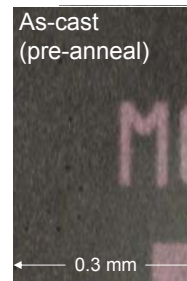
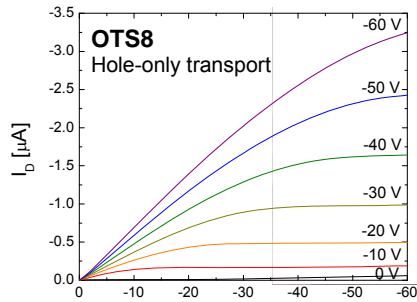
Electron accumulation evident on SiO<sub>2</sub>  
Presence of PCBM

Requires quantitative modeling

$V_{g-sd}$  \* Gundlach *et al.*, *Nat. Mater.* 7, 216-221 (2008).  
Hamadani *et al.*, *APL* 92, 203303 (2008).

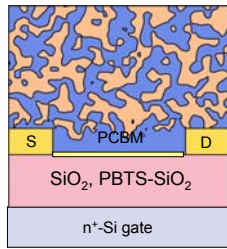
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## Annealed BHJ TFTs

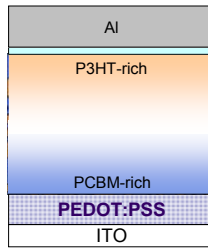


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## Implications for OPV performance

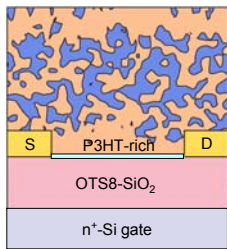


$$\gamma_{\text{SiO}_2}, \gamma_{\text{PBTS}} > \gamma_{\text{P3HT}}, \gamma_{\text{PCBM}}$$

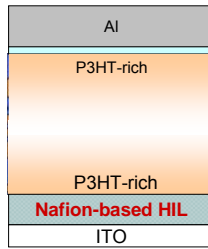


$$\gamma_{\text{PEDOT:PSS}} > \gamma_{\text{P3HT}}, \gamma_{\text{PCBM}}$$

PCBM-rich at cathode  
P3HT-rich at anode  
**Non-optimal composition**



$$\gamma_{\text{OTS8}} < \gamma_{\text{P3HT}}, \gamma_{\text{PCBM}}$$

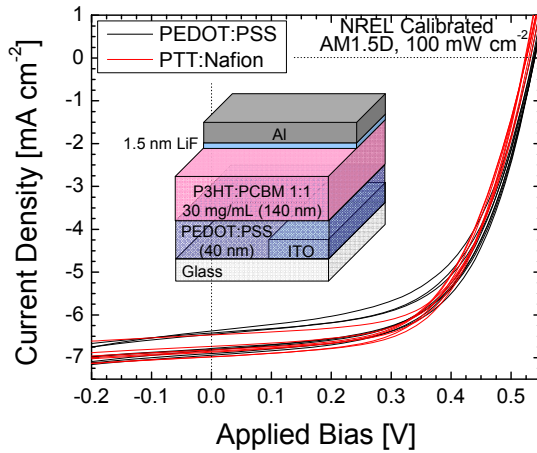


$$\gamma < \gamma_{\text{P3HT}}, \gamma_{\text{PCBM}}$$

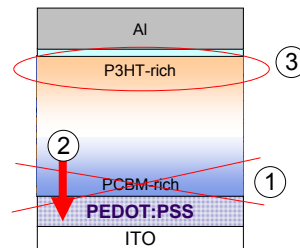
P3HT-rich at cathode,  
But still PCBM-rich at anode  
**Better, but still  
Non-optimal composition**

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## Correlation to BHJ OPV Performance?



Nafion HIL shows *marginally better performance* (but not statistically significant)



Device	$V_{oc}$ [V]	$J_{sc}$ [mA/cm <sup>2</sup> ]	FF	$\eta_{PCE}$ (%)
PEDOT:PSS (AC)	0.537 (0.003)	6.64 (0.26)	0.58 (0.01)	2.08 (0.13)
<b>Nafion HIL (AC)</b>	<b>0.525 (0.001)</b>	<b>6.92 (0.07)</b>	<b>0.59 (0.01)</b>	<b>2.15 (0.05)</b>

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## Summary and Future Work

- TFTs are useful for quick qualitative determination of interface composition.
  - Supplemented with NEXAFS, quantitative determination of interface composition is possible.
  - Film composition at the BHJ/cathode interface varies depending on the substrate surface energy; vertical phase segregation is present.
    - BHJ films deposited on  $\gamma_{\text{subst}} > \gamma_{\text{P3HT}} \cdot \gamma_{\text{PCBM}}$  result in PCBM-rich interfaces.
    - BHJ films deposited on  $\gamma_{\text{subst}} < \gamma_{\text{P3HT}} \cdot \gamma_{\text{PCBM}}$  result in P3HT-rich interfaces.
    - The film/air interface is P3HT-rich.
  - Film composition may have implications on OPV performance, e.g., the P3HT-rich interface at the anode could limit electron extraction.
- 
- Develop quantitative electrical characterization of interface composition (i.e., capacitance-voltage measurements).
  - Control vertical phase segregation by interface engineering.
  - Explore inverted device architectures, keeping in mind that changing of the bottom interface could further affect film composition at the anode.



## Acknowledgements

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